

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT7539725

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PUI YIN YU	07/06/2022
HONG TU ZHANG	07/06/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	DSBJ PTE LTD.
<b>Street Address:</b>	11 BISHAN STREET 21, #03-01
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	573943
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17819920
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(612)436-9605
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	6124369609
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<b>Correspondent Name:</b>	AARON W. PEDERSON
<b>Address Line 1:</b>	CARLSON, CASPERS, VANDENBURGH & LINDQUIST P.A.
<b>Address Line 2:</b>	225 S. SIXTH ST., SUITE 4200
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	1381.026US1
<b>NAME OF SUBMITTER:</b>	AARON W. PEDERSON
<b>SIGNATURE:</b>	/Aaron W. Pederson/
<b>DATE SIGNED:</b>	09/15/2022
<b>Total Attachments: 2</b>	
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source=Assignment (1381.026US1) - Signed#page2.tif	

ASSIGNMENT

WHEREAS, WE, Pui Yin YU residing at Hong Kong, China; and Hong Tu ZHANG residing at Zhuhai, China, made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States filed herewith, entitled CIRCUIT BOARD WITH SOLDER MASK ON INTERNAL COPPER PAD (the "Application").

AND WHEREAS, DSBJ Pte. Ltd., a corporation organized and existing under and by virtue of the laws of the Country of Singapore, and having an registered address at 11 Bishan Street 21, #03-01, Singapore 573943, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to the inventions, improvements and the Application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto the Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the Application, and in and to the Application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the inventions and improvements to the Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the Assignee, its successors and assigns.

AND, for the consideration identified above, we do agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to the Assignee, its successors and representatives all facts known to us relating to the improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in the Assignee, its successors or assigns the entire right, title and interest in and to the improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with the Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me and that full right to convey the same as herein expressed is possessed by us.

Assignment  
Title: CIRCUIT BOARD WITH SOLDER MASK ON INTERNAL COPPER PAD  
ATTORNEY DOCKET: 1381.026US1  
PAGE 2 OF 2

IN TESTIMONY WHEREOF, I have hereunto set my hand this 6 day of July  
2022.

[Signature]  
Pui Yin YU

I certify that I know or have satisfactory evidence that Pui Yin YU signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date Jul 6, 2022

Signed at HONG KONG, CHINA

LEE MAN TONG  
(Name of Witness)

[Signature]  
(Signature of Witness)

IN TESTIMONY WHEREOF, I have hereunto set my hand this 6 day of July  
2022.

[Signature]  
Hong Tu ZHANG

I certify that I know or have satisfactory evidence that Hong Tu ZHANG signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date July 6, 2022

Signed at ZHUHAI CHINA

许莫  
(Name of Witness)

许莫  
(Signature of Witness)